

Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023

Based on structural similarity

| Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs | | User Part Number | | | | | | |
|---|-----------------------------|--|-----------------------|-----------|------------|-----------|--|--|
| | | PNE20020ER | | | | | | |
| | | Part Description | | | | | | |
| | | Nexperia DHAM | Rectifier | | | | | |
| | | SMD package | | | | | | |
| Test | | Test Conditions | Duration | # Lots | # Quantity | # Rejects | | |
| | TEST | | | | | | | |
| | Pre- and Post-Stress | | | | | | | |
| # 1 | Electrical Test | Tamb = 25 °C | N/A | see below | all parts | see below | | |
| 1 | | JESD22-A113 | | | | | | |
| | PC | Bake Tamb = 125 °C Soak Tamb = 85 °C, RH = 85% | 24 hours 168 hours | | | | | |
| # 2 | Preconditioning | Reflow soldering | 3 cycles | 1514 | 64430 | 0 | | |
| π ∠ | | MIL-STD-750-1 | - 0,0.00 | 1314 | 04430 | U | | |
| | HTRB | M1038 Method A | | | | | | |
| | | Tj = Tjmax, Vr = 100% of max. datasheet | | | | | | |
| # 5 | Bias | reverse voltage | 1000 hours | 40 | 1840 | 0 | | |
| | | | | | | | | |
| | тс | JESD22-A104 | | | | | | |
| # 7 | Temperature Cycling | -65 °C to Tjmax, not to exceed 150°C | 500 cycles | 311 | 14080 | 0 | | |
| | | JECD22 4440 | | | | | | |
| # 8 or | UHAST Unbiased HAST | JESD22-A118 Tamb = 130 °C, RH = 85 % | — 96 hours | 311 | 14080 | 0 | | |
| # 0 01 | Olibidaed FIAST | JESD22-A102 | | | | | | |
| | AC | Tamb = 121 °C, RH = 100 % | | | | | | |
| # 8a | Autoclave | Pressure = 205 kPa (29.7 psia) | | | | | | |
| | | · · · · · | | | | | | |
| | H3TRB | JESD22-A101 | | | | | | |
| | High Humidity High | Tamb = 85 °C, RH = 85%, VR = 80 % of | | | | | | |
| # 9 | Temperature Reverse Bias | rated reverse voltage ^[1] | 1000 hours | 311 | 14080 | 0 | | |
| | | MIL-STD-750 Method 1037 | | | | | | |
| | IOL | ton = toff, devices powered to insure $\Delta Tj = 100.00$ | | | | | | |
| # 10 | Intermittent Operating Life | 100 °C | 333 hours | 312 | 14120 | 0 | | |
| | RSH | JESD22-A111 | | | | | | |
| # 20 | Resistance to Solder Heat | 260 °C ± 5 °C | 10 s | 269 | 8070 | 0 | | |
| # ZU | SD | 255 5 - 5 6 | 10.5 | 209 | 5070 | U | | |
| # 21 | Solderability | J-STD-002 | | 222 | 6660 | 0 | | |

^[1] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test # 5)
Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

| Wafer Fab | Technology | Quantity | Rejects | Failure Rate (FIT) | MTTF (hrs) |
|-----------|------------|----------|---------|--------------------|------------|
| Nexperia | | | | | |
| DHAM | Rectifier | 1840 | 0 | 2,31 | 4,33E+08 |

^{© 2024} Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com